The logo features the year '2005' in large, bold, yellow 3D-style numerals. A circular inset, resembling a microchip with a blue and green grid pattern, is positioned behind the zeros. The words 'INTEL SPRING ANALYST MEETING' are written in white, sans-serif, all-caps font across the middle of the '2005' numerals. The entire graphic is set against a dark blue background with a subtle, larger-scale grid pattern.

2005 INTEL SPRING ANALYST MEETING

Sean Maloney
Executive Vice President
General Manager, Mobility Group

Mobile Progress Since Fall Analyst Meeting

Notebook Platform Ramp

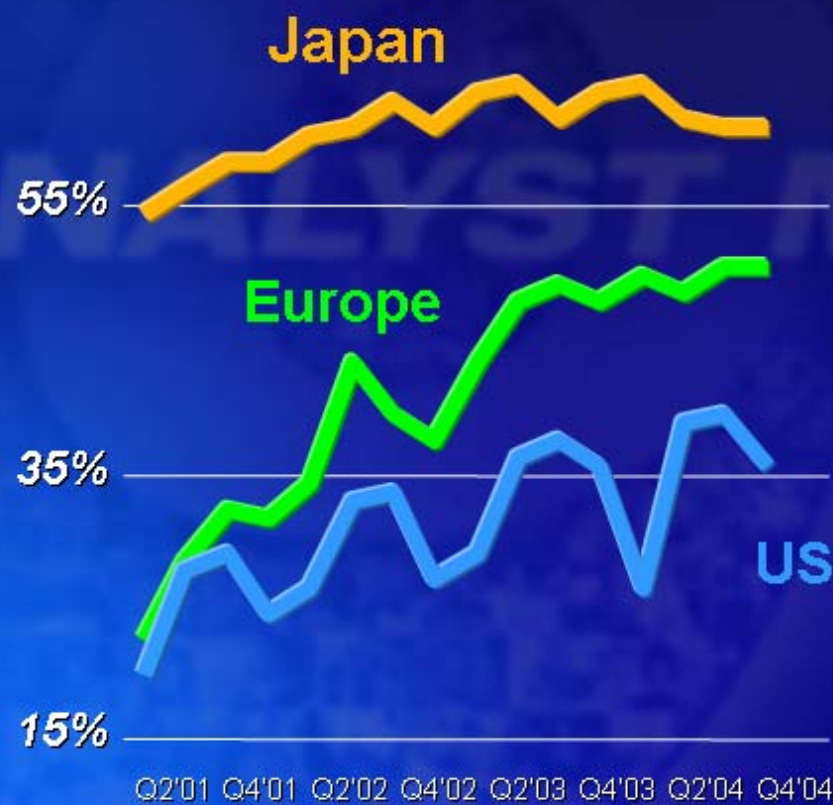
Rapid Intel Mobile CPU Ramp

Mobile CPU shipments
Mu/Q



Notebook Becoming The Consumer's Choice

Consumer Notebook
Penetration %
75%



Source: Intel for mobile CPU and chipset shipments; Gartner, IDC and Intel estimates for notebook penetration.

Mobile Progress Since Fall Analyst Meeting

Phone Platform: Application Processors and Flash Memory

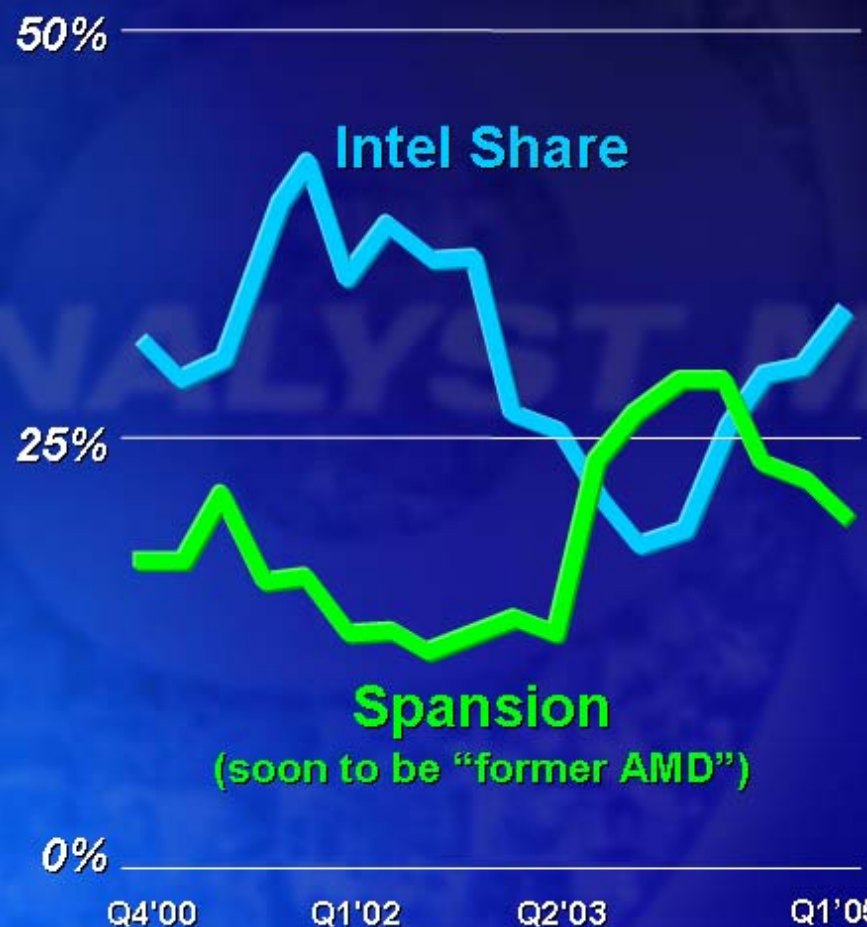
Application Processor Ramp

Mu/Q

On Track for
>30 Mu
Annual Run Rate
by Q4 2005



NOR Flash Segment Share



Source: WSTS, AMD public documents and Intel internal estimates, Note: Q1 '05 for NOR flash is data through February.



Mobility Group

Common Manufacturing Process

Flash
Memory

CPUs

Chipsets



EDGE
W-CDMA (3G)

WiMAX

Wi-Fi

Unified Mobile Experience

intel.

Other names and brands are property of respective owners.



Driving the Notebook Momentum

Intel® Centrino™ Mobile Technology



2005 Sonoma

150+ Design Wins



“Mobile graphics processors...up 40.8%...Intel surpassed ATI as the largest supplier to the mobile market [segment] in Q1 with share growing from 39.5% to 50.8%”

April 2005

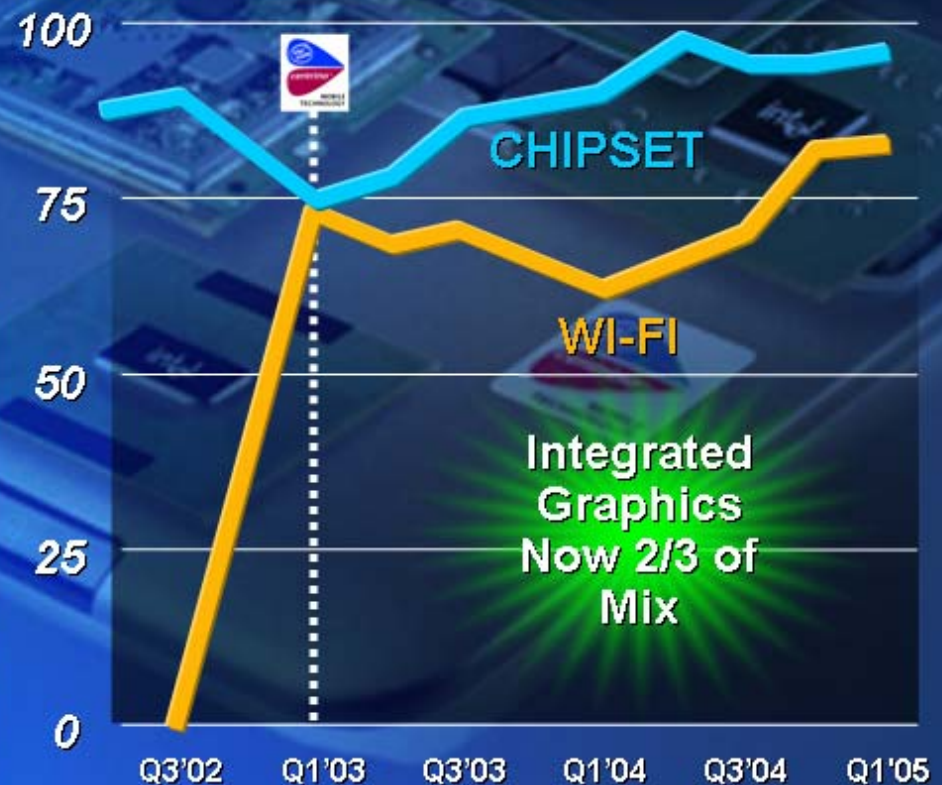
ABIresearch

- Intel #1 in Q4'04 Wi-Fi IC market segment share
- Intel market segment share in Mini-PCI for PCs up 4x in 2004 to 47%.

March 2005

intel

Intel Chipset & Wi-Fi Attach Rates (%)



Source: Intel

Other names and brands are property of respective owners.

How Do We Accelerate Even Further, Faster?

2006 *Napa*

On Track for More Designs

Performance

Yonah: 1st from the ground up dual core mobile 65nm processor
Calistoga: Top-quality graphics at lower power

Wireless

The latest security standards
Advanced end-to-end enterprise features
UMTS / w-CDMA add-in options
Intel® Smart Wireless Solutions™

Thinner and Lighter

Better heat dissipation using Intel®
Advanced Thermal Manager

Battery Life

Lower average power across all components
Better integrated graphics drives lowers
system power
Intel® Dynamic Power Coordination

**31% smaller form factor
than first generation**

100%

69%

Carmel 2003

Napa 2006



Intel's Notebook Ecosystem



Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive

Optical Drive

LCD (2006 commence)

Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
Optical Drive
LCD (2006 commence)

Intel Extended
Battery Life Program

Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
Optical Drive
LCD (2006 commence)

Intel Extended
Battery Life Program

Intel Concept PC Program



lenovo



TCL



Quanta Computer
廣達電腦

Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
Optical Drive
LCD (2006 commence)

Intel Extended
Battery Life Program

Intel Concept PC Program



lenovo



TCL



Quanta Computer
廣達電腦

Mobilized Software Initiative

5x more
applications
in 2 years



Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
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lenovo



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Quanta Computer
廣達電腦

Mobilized Software Initiative

5x more
applications
in 2 years



Wireless
ISV Enabling
>1M licensees

Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
Optical Drive
LCD (2006 commence)

Intel Extended
Battery Life Program

Intel Concept PC Program



lenovo



TCL



Quanta Computer
廣達電腦

Government
Spectrum
Influence

Wireless
ISV Enabling
>1M licensees

Mobilized Software Initiative

5x more
applications
in 2 years



Source: Intel

Other names and brands are property of respective owners.

Intel's Notebook Ecosystem

Common Building Blocks

Hard Drive
Optical Drive
LCD (2006 commence)

Intel Extended
Battery Life Program

Intel Wireless Verification
Program
57k hotspots



Intel Concept PC Program



Government
Spectrum
Influence

Wireless
ISV Enabling
>1M licensees

Mobilized Software
Initiative
*5x more
applications
in 2 years*



Source: Intel

Other names and brands are property of respective owners.

The Unified Mobile Experience

Coming Q1 2006 To Notebook/Phone Platforms



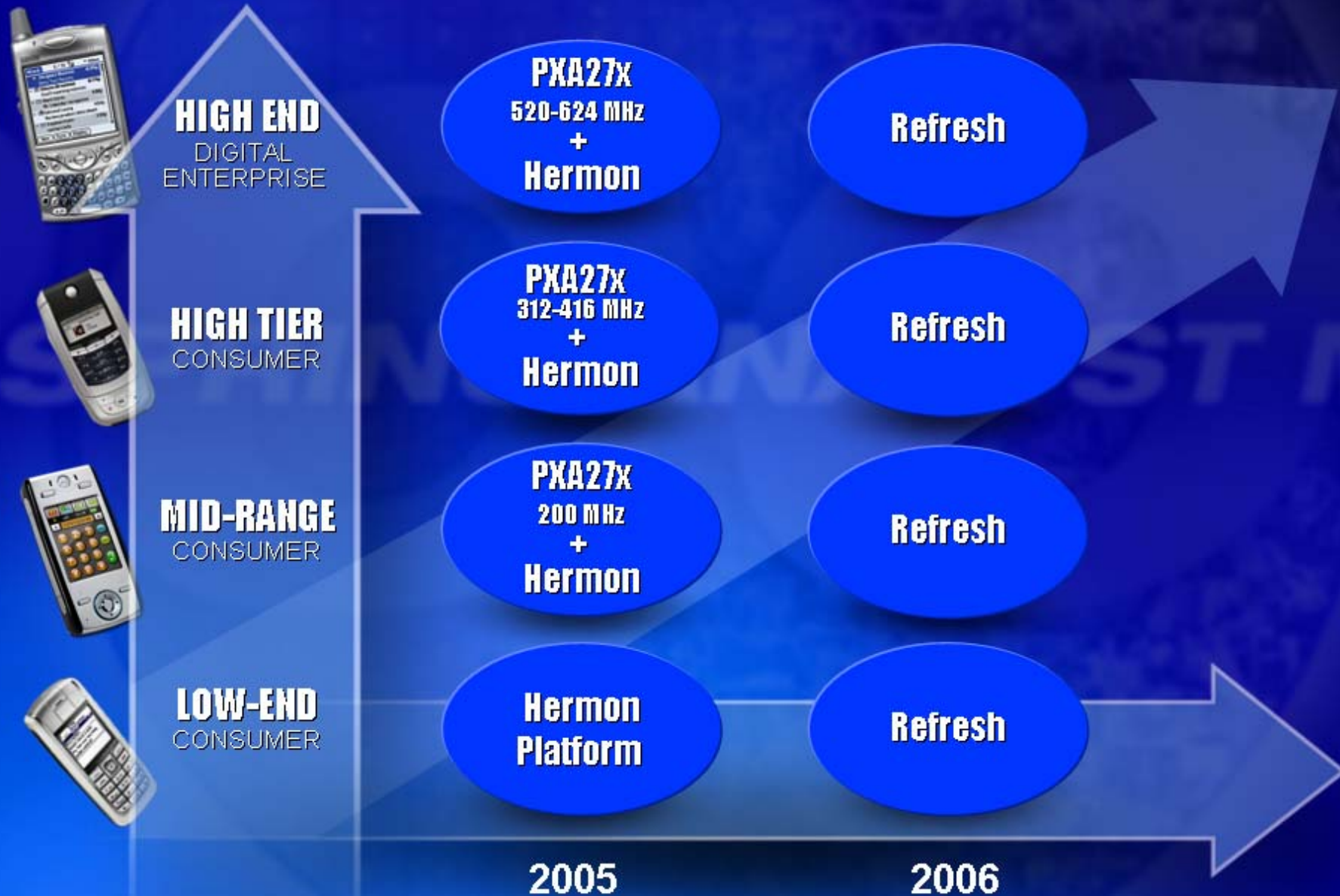
intel

Source: Intel Roadmap

2005
INTEL SPRING ANALYST MEETING

Intel "Top to Bottom"

in GPRS/EDGE/w-CDMA Phone Platforms



Source: Intel Roadmap

Intel's Handheld Ecosystem

Intel®
Mobile
Media
Technology

Port of Choice



*Supports applications across
all OSs + over 150 unique to
XScale® technology*

*Driven by 11,000 person
developer community*

intel

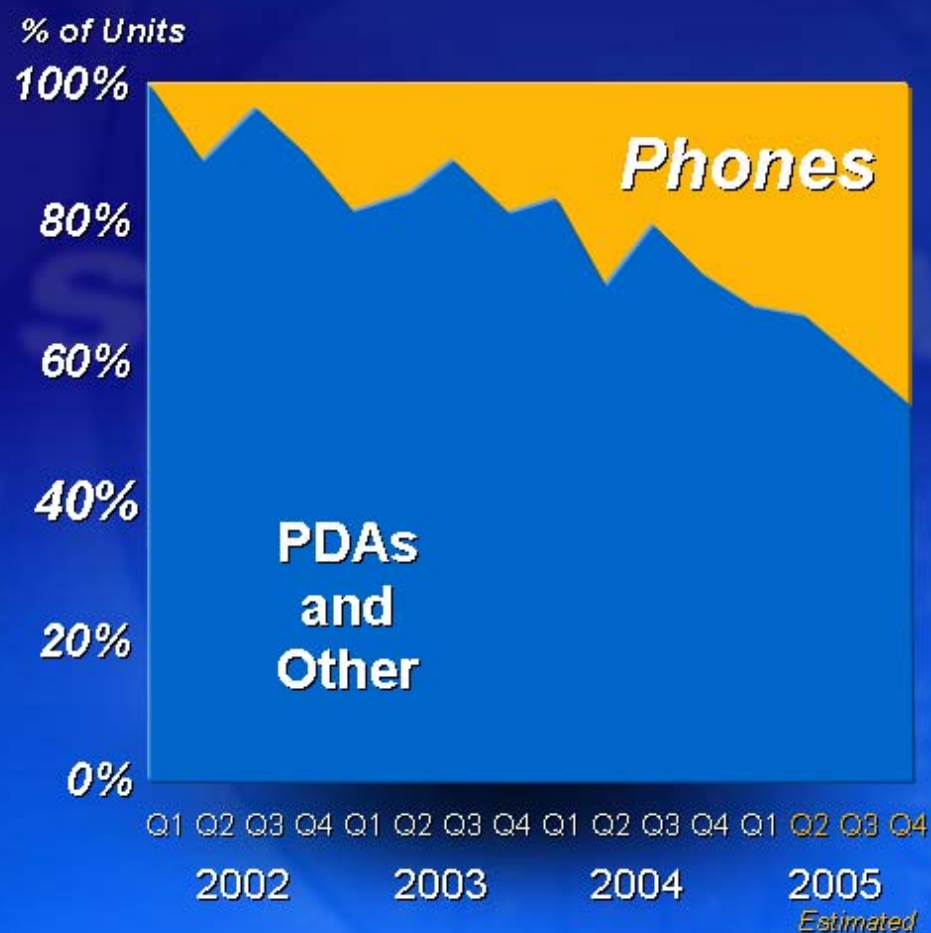
Source: Intel

Other names and brands are property of respective owners.

INTEL SPRING ANALYST MEETING
2005

Phone Platform Progress

Application Processor Mix Shifts To Phones



Phone Customers



LG Electronics



palmOne



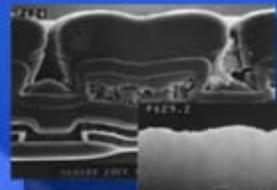
mmO₂

ZTE中兴

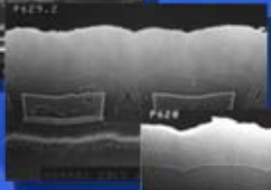
NOR Flash Memory

Business Principles

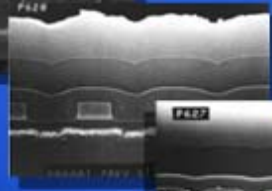
1. Maintain the technology lead



1986/1.5µm



1988/1.0µm



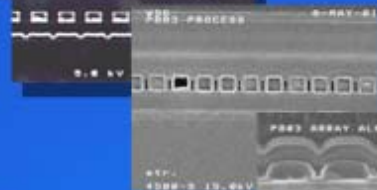
1991/0.8µm



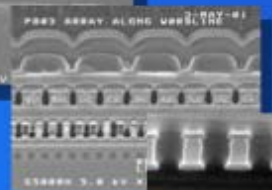
1993/0.6µm



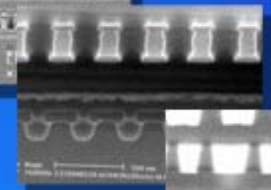
1996/0.4µm



1998/0.25µm



2000/0.18µm



2002/0.13µm



2005/90nm

2006 Forecast/65nm

2008 Forecast/45nm

NOR Flash Memory

Business Principles

2. Hit mass market phone requirements

Intel NOR Flash Density Matching the Phone Cadence

Phones (M)

160

120

80

40

0

16Mb

32Mb

64Mb

128Mb

256Mb

512Mb

1Gb

2Gb

2004 Phone

2006 Phone

2004: 130nm 256Mb "Tyax"

2005: 90nm 512Mb "Sibley"

2006: 65nm 1Gb "Capulet"

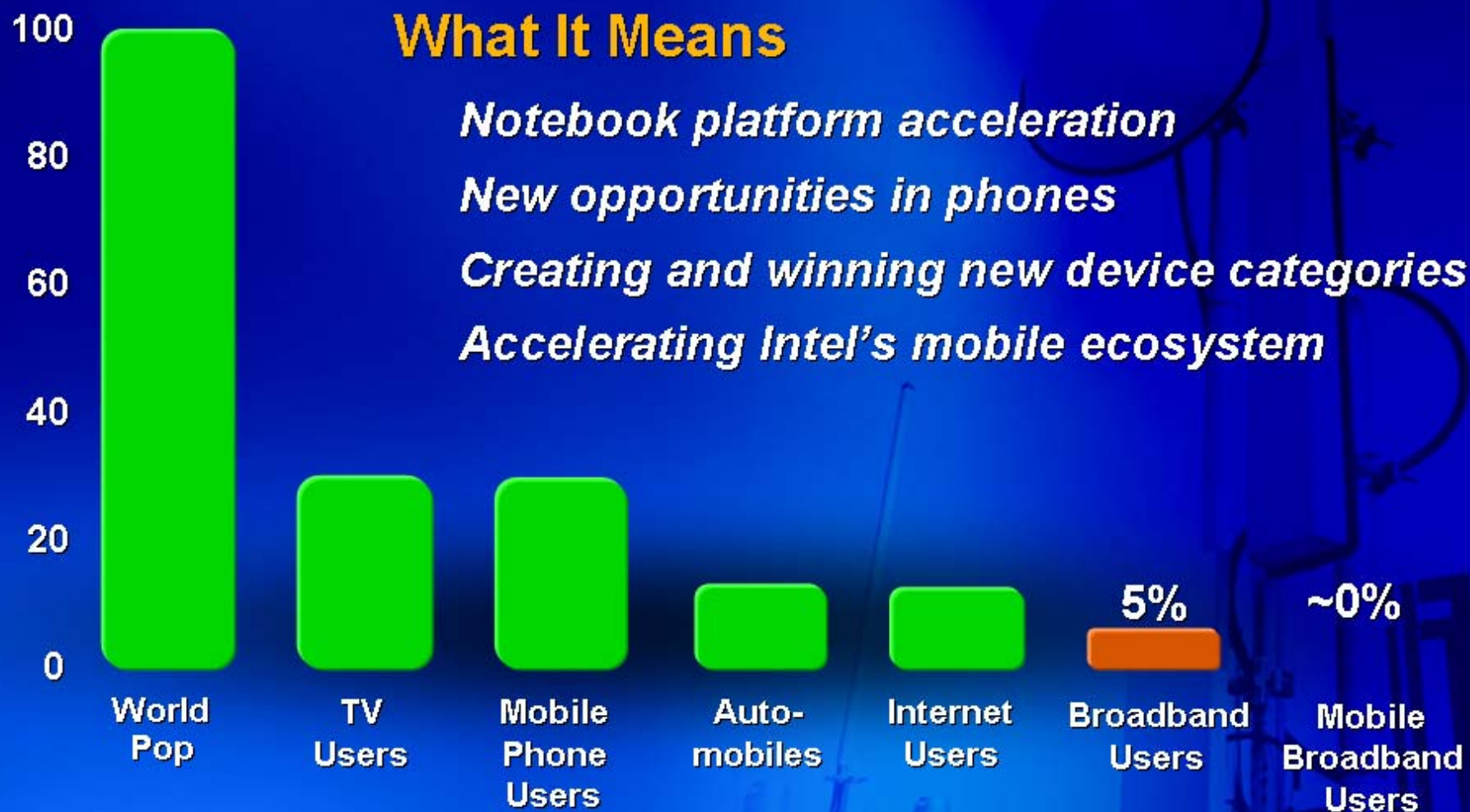


Source: Intel roadmap, GfK/NPD sales out data, Portelligent teardowns



The Global WiMAX Opportunity

% of global population



Source: ZTE, ITU, IDC, Autoweek
Other names and brands are property of respective owners.

Intel's WiMAX Ecosystem

WiMAX Forum Members

- Ecosystem/Applications
- Service Providers
- System Vendors
- Silicon/Component Suppliers



46



Spring 2004

291



Today

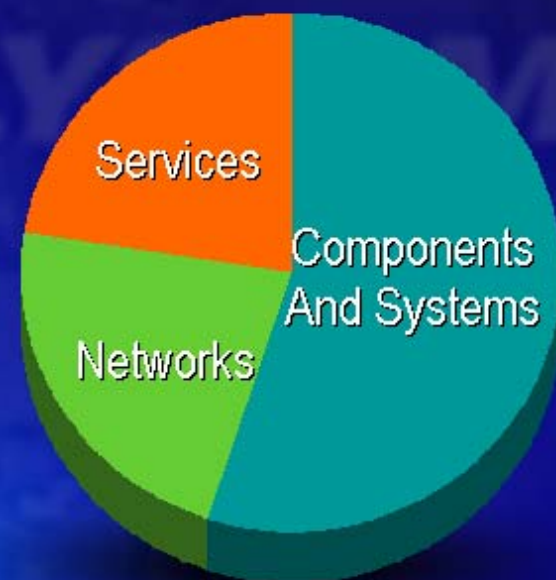
Estimated Engineers Working on WiMAX

*Less than
500 Engineers*

Components
And Systems

Spring 2004

*Approaching
5,000 Engineers*



Today



Source: WiMAX Forum; Includes in-process members; # of engineers based on Intel estimates
Other names and brands are property of respective owners.





The WiMAX Ecosystem





Intel's Most Recent WiMAX Collaboration

Sprint and Intel to Explore WiMAX Broadband Technologies

May 5, 2005

Sprint / Intel joint press release

Summary

- Notebook momentum strong
- Volumes ramping in handhelds
- Opportunity to create unified experience across both platforms
- NOR flash business gains share
- Opportunity to accelerate more rapidly in '05/'06